

Amendments to the Specification:

Please replace the paragraph beginning on page 4, line 16 with the following rewritten paragraph:

-- BRIEF DESCRIPTION OF THE DRAWINGS

These and other features of the invention can best be understood by the following description of the accompanying drawings as follows:

Figure 1 is a side cross-sectional view of a micro-machined semiconductor package according to the present invention.

Figure 2 is a top view of a low temperature co-fired ceramic substrate.

Figure 3 is a top view of a micro-machined semiconductor device.

Figure 4 is a flowchart of a manufacturing process for a micro-machined semiconductor package.

It is noted that the drawings of the invention are not to scale. --